

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	178144	(ad<"20021029") and (laser or optoelectronic or photodiode or "led " or diode) and (epoxy or encapsulant or encapsulate or resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:12
L5	12293	L4 and ((mill or milling or milled or carve or cut or cutting or groove) with (epoxy or encapsulant or encapsulate or resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:11
L6	3592	L4 and ((mill or milling or milled) with (epoxy or encapsulant or encapsulate or resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:11
L7	428410	L6 anc concave	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:12
L8	123	L6 and concave	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:18
L9	73227	(ad<"20021029") and (laser or optoelectronic or photodiode or "led " or diode) and (epoxy or encapsulant or encapsulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:12
L10	1969	L9 and ((lens or reflect or reflective) with (epoxy or encapsulant or encapsulate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:12
L11	668	L10 and (leadframe or leads)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:12

L12	123	L8 not L11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:12
L13	581	L6 and (lens or reflect or reflective)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:18
L14	529	L13 not L12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:18
L15	526	L14 not L11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:19
S1	6562	(ad<"2002102") and (laser or optoelectronic or photodiode) and (encapsulant or encapsulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 20:32
S2	19	S1 and ((mill or milling) with (encapsulant or encapsulate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:05
S3	50490	(ad<"2002102") and (laser or optoelectronic or photodiode) and (epoxy or encapsulant or encapsulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:10
S4	267	S3 and ((mill or milling) with (epoxy or encapsulant or encapsulate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:11

S5	70	S4 and (leadframe or leads)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:17
S6	73197	(ad<"2002102") and (laser or optoelectronic or photodiode or "led " or diode) and (epoxy or encapsulant or encapsulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:48
S7	352	S6 and ((mill or milling) with (epoxy or encapsulant or encapsulate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 20:33
S8	85	S7 not S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:11
S9	2516	S6 and ((groove or lens or reflect or reflective) with (epoxy or encapsulant or encapsulate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:16
S10	1969	S6 and ((lens or reflect or reflective) with (epoxy or encapsulant or encapsulate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:50
S11	668	S10 and (leadframe or leads)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:50
S12	19	S11 and (mill or milling)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:51

S13	73197	(ad<"20021029") and (laser or optoelectronic or photodiode or "led " or diode) and (epoxy or encapsulant or encapsulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:48
S14	1969	S13 and ((lens or reflect or reflective) with (epoxy or encapsulant or encapsulate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 20:41
S15	668	S14 and (leadframe or leads)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:50
S16	19	S15 and (mill or milling)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 18:51
S17	369	(ad<"2002102") and "362"/\$.ccls. and (mill or milling)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 20:34
S18	0	S17 and ((mill or milling) with (epoxy or encapsulant or encapsulate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 20:35
S19	33	S17 and (epoxy or encapsulant or encapsulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 20:35
S20	73197	(ad<"20021029") and (laser or optoelectronic or photodiode or "led " or diode) and (epoxy or encapsulant or encapsulate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/28 10:08

S21	1969	S20 and ((lens or reflect or reflective) with (epoxy or encapsulant or encapsulate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 20:42
S22	668	S21 and (leadframe or leads)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 20:42
S23	42	S22 and ((cut or cutting ro groove depression) with (epoxy or encapsulant or encapsulate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/25 20:42